



## GaN 28V, 70W, RF Power Transistor

### Description

The XTAH42070GX is a 70W internally matched, GaN HEMT, designed for ultrawide RF CW or pulse applications under 4.2GHz. In typical application within 0.4-4GHz, it can deliver >50W CW across the full band. Within 2-4GHz, it can deliver >60W CW across the full band

There is no guarantee of performance when it is used in applications designed outside of these frequencies.

- 400-4000M

V<sub>ds</sub>=28V, I<sub>dq</sub>=100mA, signal: CW, with device soldered (Data up to 40V upon request)

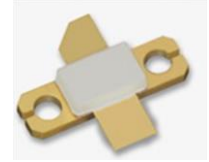
Freq(MHz)	Pin(dBm)	Pout(dBm)	Pout(W)	Ids(A)	Gain(dB)	Eff(%)
400	30.94	47.56	57.02	3.53	16.62	57.69
600	33.32	48.09	64.42	3.64	14.77	63.20
1000	34.04	48.19	65.92	3.92	14.15	60.06
1500	37.5	48.19	65.92	3.62	10.69	65.03
2000	39.19	47.95	62.37	4.18	8.76	53.29
2500	37.94	48.69	73.96	4.75	10.75	55.61
3000	38.7	47	50.12	5.05	8.3	35.44
3500	39.25	47.61	57.68	4.86	8.36	42.38
4000	38.4	47.5	56.23	4.17	9.1	48.16

- 2000-4000M

V<sub>ds</sub>=28V, I<sub>dq</sub>=200mA, signal: CW, with device soldered

Freq(MHz)	Pin(dBm)	Pout(dBm)	Pout(W)	Ids(A)	Gain(dB)	Eff(%)
<b>2000</b>	<b>39.00</b>	<b>48.35</b>	<b>68.4</b>	<b>4.91</b>	<b>9.3</b>	<b>49.7</b>
<b>2500</b>	<b>39.00</b>	<b>48.64</b>	<b>73.1</b>	<b>5.36</b>	<b>9.6</b>	<b>48.7</b>
<b>3000</b>	<b>39.00</b>	<b>48.85</b>	<b>76.7</b>	<b>5.45</b>	<b>9.8</b>	<b>50.3</b>
<b>3500</b>	<b>39.00</b>	<b>48.30</b>	<b>67.6</b>	<b>5.11</b>	<b>9.3</b>	<b>47.3</b>
<b>4000</b>	<b>39.00</b>	<b>48.30</b>	<b>67.6</b>	<b>4.77</b>	<b>9.3</b>	<b>50.6</b>

**XTAH42070GX**



### Important Note: Proper Biasing Sequence for GaN HEMT Transistors

#### Turning the device ON

1. Set VGS to the pinch-off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage (28V)
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

#### Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS



**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DSS}$	150	Vdc
Gate--Source Voltage	$V_{GS}$	-10,+2	Vdc
Operating Voltage	$V_{DD}$	40	Vdc
Maximum Forward Gate Current @ $T_c = 25^{\circ}C$	$I_{gmax}$	16.8	mA
Storage Temperature Range	$T_{stg}$	-65 to +150	$^{\circ}C$
Case Operating Temperature	$T_c$	+150	$^{\circ}C$
Operating Junction Temperature(See note 1)	$T_j$	+225	$^{\circ}C$

Note: 1. Continuous operation at maximum junction temperature will affect MTTF  
2. Bias Conditions should also satisfy the following expression:  $P_{diss} < (T_j - T_c) / R_{JC}$  and  $T_c = T_{case}$

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_c = 85^{\circ}C, T_j = 200^{\circ}C, RF\ CW\ operation$	$R_{\theta JC}$	2.3	C/W

**Table 3. Electrical Characteristics** ( $T_c = 25^{\circ}C$  unless otherwise noted)

**DC Characteristics**

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8V; I_{DS} = 16.8mA$	$V_{DSS}$	150			V
Gate Threshold Voltage	$V_{DS} = 28V, I_D = 16.8mA$	$V_{GS(th)}$	-4	-	-2	V
Gate Quiescent Voltage	$V_{DS} = 28V, I_{DS} = 100mA,$ Measured in Functional Test	$V_{GS(Q)}$		-2.35		V

## 400-4000MHz

Figure 2: Output of network analyzer S11, S21 Vgs=-2.4V, Vds=32V, Idq=130mA, input power=0dBm

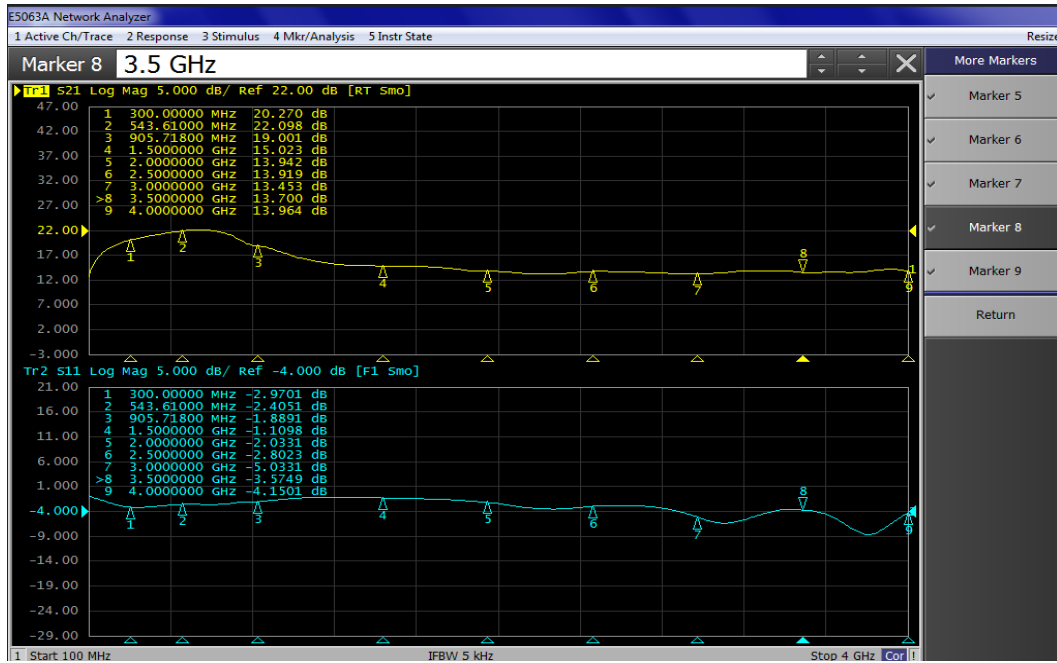
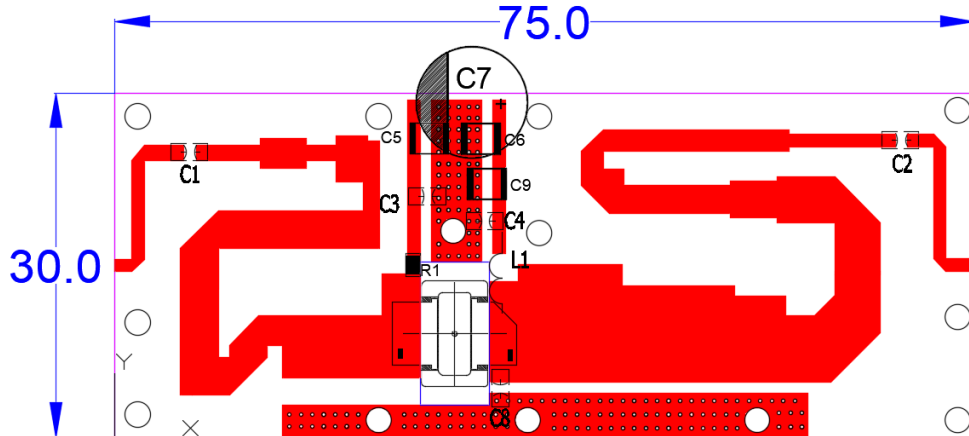


Figure 3: Layout info and bill of materials for 0.7-4GHz application circuit



Component	Description	Suggestion
C7	470uF/63V	
C5,C6,C9	10uF	10uF/100V
C1,C2, C3, C4	18pF(MQ300805)	
C8	0.9pF(MQ300805)	
L1	0.5mm wire, 4mm innerdiameter, 3turns	DIY
R1	Chip Resistor,10Ω	0805
PCB	20mil Rogers 4350B	

## 2000-4000MHz

Figure 2: Output of network analyzer S11, S21 Vgs=-2.4V, Vds=32V, Idq=130mA, input power=0dBm

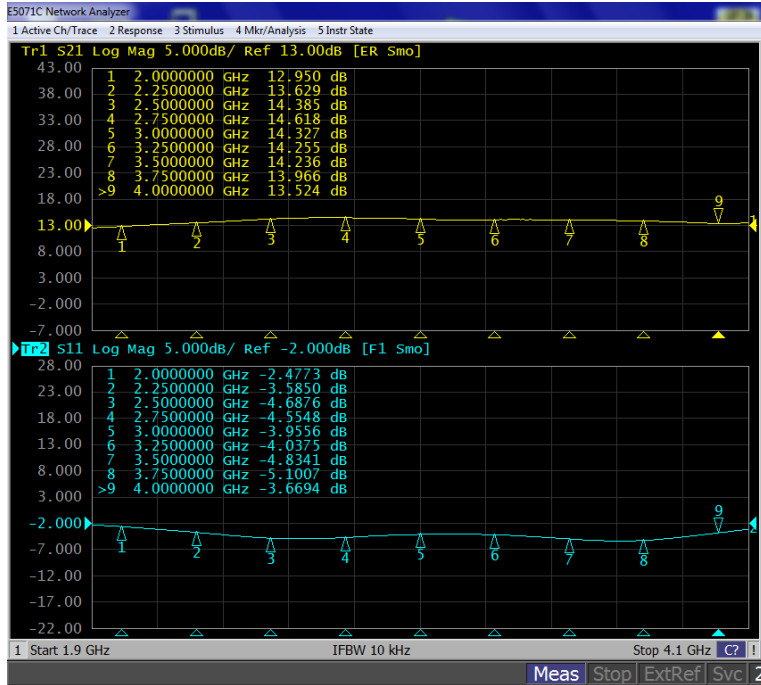


Figure 3: Layout info and bill of materials for 2-4GHz application circuit



Reference Designator	Description	Quantity	Suggestion
C0, C1	10uF/200V, 1210	2	
C2, C3, C4, C5	5.6 pF, 0603/0805	4	
R1	10 Ω, 0603/0805	1	Murata
T1	XTAH42070GX	1	Innegration
PCB	Rogers 4350B, 30mil		-



## Package Outline

### Flanged ceramic package; 2 leads

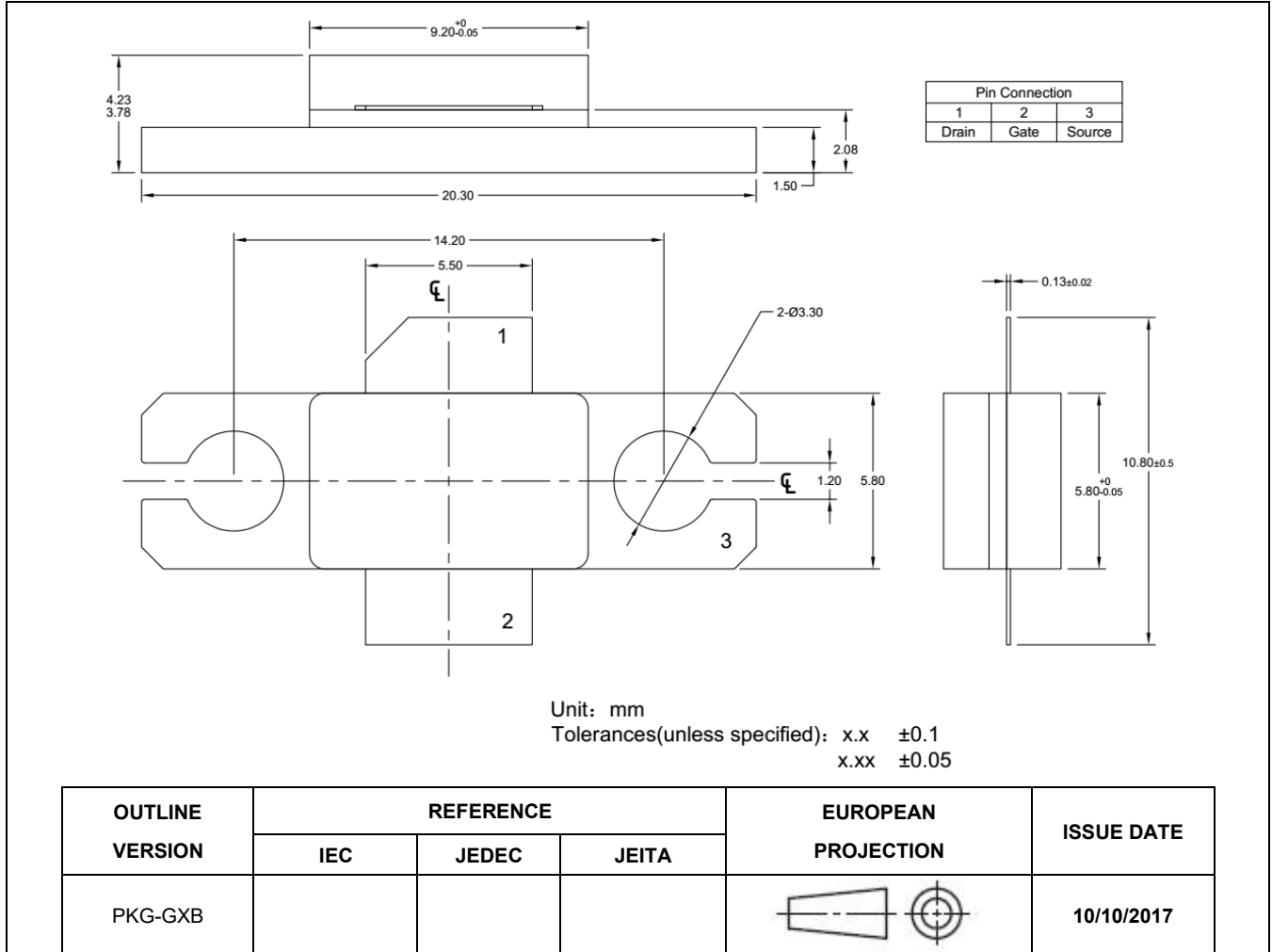


Table 4. Document revision history

Date	Revision	Datasheet Status
2025/3/28	V1.0	Preliminary Datasheet Creation
2025/6/5	V1.1	Add 2.4-4.2G application data
2026/4/22	V1.2	Change 2-4G data to replace 2.4-4.2GHz for more popular reference

Application data based on YHG-25-13/RXT-25-19

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